

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	0	wo-2002063394-\$ did.	DERWENT	ADJ	ON	2008/12/03 14:25
L10	1	wo-02063394-\$ did.	DERWENT	ADJ	ON	2008/12/03 14:25
L11	1	("6897140").PN.	US-PGPUB; USPAT	OR	OFF	2008/12/03 14:26
L12	21208	(tungsten near1 silicide) or WSi or WS\$2	US-PGPUB; USPAT	ADJ	ON	2008/12/03 14:33
L13	93	I12 and (EUV or (extreme ultra-violet) or (extreme near1 UV))	US-PGPUB; USPAT	ADJ	ON	2008/12/03 14:34
L14	3	I12 same (EUV or (extreme ultra-violet) or (extreme near1 UV))	US-PGPUB; USPAT	ADJ	ON	2008/12/03 14:34
L15	1	("6613393").PN.	US-PGPUB; USPAT	OR	OFF	2008/12/03 15:25
L16	204808	CVD or (chemical near1 vapor near1 deposition)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 15:30
L17	561	I16 and (MoSi\$2 with WSi \$2)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 15:31
L18	1	I17 and (EUV or (extreme ultra-violet) or (extreme near1 UV))	US-PGPUB; USPAT	ADJ	ON	2008/12/03 15:31
L19	106	I16 same (MoSi\$2 with WS\$2)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 15:32
L20	36	I19 and (pvdf or (physical near1 vapor near1 deposition))	US-PGPUB; USPAT	ADJ	ON	2008/12/03 15:35
S1	12310	process and film and substrate and "204".clas.	US-PGPUB; USPAT	ADJ	ON	2007/04/18 09:58
S2	2786	process and film and substrate and "204".clas. and magnetron and sputtering	US-PGPUB; USPAT	ADJ	ON	2007/02/12 14:00
S3	0	process and film and substrate and "204".clas. and magnetron and sputtering and ion an polish	US-PGPUB; USPAT	ADJ	ON	2007/04/16 14:59
S4	2498	process and film and substrate and "204".clas. and magnetron and sputtering and target	US-PGPUB; USPAT	ADJ	ON	2007/02/12 14:01

S6	1	(optical device) and (lithographic projection) and (multilayer system)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:22
S7	64	(optical device) and (lithographic projection)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:24
S8	2863	etching and magnet and substrate and target and plasma	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:27
S9	2787	etching and magnet and substrate and target and plasma and (device or apparatus)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:27
S10	98	sputter and magnetron and "204".clas. and krypton and substrate and target	US-PGPUB; USPAT	ADJ	ON	2007/04/16 15:00
S11	24	sputter and magnetron and "204".clas. and krypton and substrate and target and (multilayer or multiple layer)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:48
S12	10	sputter and magnetron and "204".clas. and krypton and substrate and target and (multilayer or multiple layer) and (silicon or si) and (molybdenum or mo)	US-PGPUB; USPAT	ADJ	ON	2007/04/16 16:10
S13	7	sputter and magnetron and ion beam and "204". clas. and krypton and substrate and target and (silicon or si) and (molybdenum or mo)	US-PGPUB; USPAT	ADJ	ON	2007/04/16 15:35
S14	22	sputter and magnetron and "204".clas. and krypton and substrate and target and ion and energy and (eV or electronvolt)	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:10
S15	5	sputter and magnetron and "204".clas. and krypton and substrate and target and ion and energy and (eV or electronvolt) and (molybdenum or Mo) and (silicon or Si)	US-PGPUB; USPAT	ADJ	ON	2007/04/16 16:39
S16	0	kawaguchi and 2003-83335	JPO	ADJ	ON	2007/04/16 16:40

S17	0	jp-200383335-\$ did.	JPO	ADJ	ON	2007/04/16 16:42
S18	0	jp-83335-\$ did.	JPO	ADJ	ON	2007/04/16 16:41
S19	0	kawaguchi and fujiki and gonda and tahara	JPO	ADJ	ON	2007/04/16 16:41
S20	1	JP200383335.ap.	JPO	ADJ	ON	2007/04/16 16:45
S21	0	JP200383335.ap.	JPO	ADJ	ON	2007/04/16 16:44
S22	0	JP2003083335.ap.	JPO	ADJ	ON	2007/04/16 16:44
S23	0	JP0200383335.ap.	JPO	ADJ	ON	2007/04/16 16:44
S24	0	jp-83335-\$ did.	JPO	ADJ	ON	2007/04/16 16:45
S25	0	jp-0383335-\$ did.	JPO	ADJ	ON	2007/04/16 16:46
S26	0	JP-2003083335-\$ did. JP-2002063827-A.DID.	JPO	ADJ	ON	2007/04/16 16:47
S27	1	JP-2003083335-\$ did.	JPO	ADJ	ON	2007/04/16 16:47
S28	0	JP-200383335-\$ did.	JPO	ADJ	ON	2007/04/16 16:48
S29	0	JP-2003833350-\$ did.	JPO	ADJ	ON	2007/04/16 16:48
S30	0	JP-200383335-\$ did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2007/04/16 16:57
S31	21185	kawaguchi.in.	JPO	ADJ	ON	2007/04/16 16:57
S32	13	kawaguchi.in. and gonda.in.	JPO	ADJ	ON	2007/04/16 16:57
S33	0	kawaguchi.in. and gonda.in. and fujiki.in.	JPO	ADJ	ON	2007/04/16 16:58
S34	13	kawaguchi.in. and gonda.in.	JPO	ADJ	ON	2007/04/16 16:58
S35	596	"204".clas. and (mean free path)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:40
S36	454	"204".clas. and (mean free path) and apparatus	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:40
S37	14	sputter and magnetron and "204".clas. and krypton and substrate and target and (mean free path)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:48

S38	101	sputter and "204".clas. and (mean free path) with (small or smaller or less)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:21
S39	9	sputter and "204".clas. and (mean free path) with (small or smaller or less) and krypton	US-PGPUB; USPAT	ADJ	ON	2007/04/17 10:44
S40	12	ion and "204".clas. and (mean free path) with (small or smaller or less) and krypton	US-PGPUB; USPAT	ADJ	ON	2007/04/17 10:44
S41	0	donahue.in. and (Method of Sputtering using krypton)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S42	650	donahue.in.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:38
S43	0	(hilke donahue).in.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:38
S44	0	donohue.in. and (Method of Sputtering using krypton)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S45	306	donohue.in.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S46	8	donohue.in. and "204". clas.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S47	1	("4923585").PN.	US-PGPUB; USPAT	OR	OFF	2007/04/17 17:31
S48	1	("20060081458").PN.	US-PGPUB; USPAT	OR	OFF	2007/04/18 10:47
S49	13	electron beam adj (vapor or evaporation)and "204". clas. and target and substrate and (mean free path)	US-PGPUB; USPAT	ADJ	ON	2007/04/18 10:48
S50	1888	sputter and magnetron and "204".clas. and vacuum and pressure	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:10
S51	295	sputter and magnetron and "204".clas. and vacuum and pressure with (different or distinct or various or varied)	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:11
S52	26	sputter and magnetron and "204".clas. and vacuum and pressure with (different or distinct or various or varied) and (partition or divider or separator)	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:27

S53	451678	sputter sputtering deposition	US-PGPUB; USPAT	OR	ON	2007/04/26 09:28
S55	1043457	stage stages	US-PGPUB; USPAT	OR	ON	2007/04/26 09:28
S56	9066	S53 with S55	US-PGPUB; USPAT	OR	ON	2007/04/26 09:29
S57	4214884	two	US-PGPUB; USPAT	OR	ON	2007/04/26 09:29
S58	151824	S55 near2 S57	US-PGPUB; USPAT	OR	ON	2007/04/26 09:30
S59	1723	S56 and S58	US-PGPUB; USPAT	OR	ON	2007/04/26 09:31
S60	1991908	pressure pressures	US-PGPUB; USPAT	OR	ON	2007/04/26 09:32
S61	59192	S55 with S60	US-PGPUB; USPAT	OR	ON	2007/04/26 09:32
S62	291	S59 and S61	US-PGPUB; USPAT	OR	ON	2007/04/26 09:33
S63	39	S56 same S58 same S61	US-PGPUB; USPAT	OR	ON	2007/04/26 09:33
S64	3664	pressure and ((mean free path) same (short or shorter or long or longer or small or smaller or great or greater or less or lesser or big or bigger))	US-PGPUB; USPAT	ADJ	ON	2007/12/12 13:43
S65	406	pressure and ((mean free path) same (short or shorter or long or longer or small or smaller or great or greater or less or lesser or big or bigger)) and "204".clas.	US-PGPUB; USPAT	ADJ	ON	2007/12/12 13:46
S66	234	pressure and ((mean free path) same (short or shorter or long or longer or small or smaller or great or greater or less or lesser or big or bigger)) and "204".clas. and target and substrate	US-PGPUB; USPAT	ADJ	ON	2007/12/12 13:46
S67	136	pressure and ((mean free path) same (short or shorter or long or longer or small or smaller or great or greater or less or lesser or big or bigger)) and "204".clas. and (target same substrate same (distance or length or space))	US-PGPUB; USPAT	ADJ	ON	2007/12/12 13:50

S68	1	("6752911").PN.	US-PGPUB; USPAT	OR	OFF	2007/12/12 13:52
S69	1	"20030057087"	US-PGPUB; USPAT	ADJ	ON	2007/12/12 13:53
S70	0	wo-0140534-\$ did.	EPO; JPO; DERWENT	ADJ	ON	2007/12/12 13:53
S71	1	wo-200140534-\$ did.	EPO; JPO; DERWENT	ADJ	ON	2007/12/12 13:54
S72	1	("6077403").PN.	US-PGPUB; USPAT	OR	OFF	2007/12/12 13:54
S73	7371	(electron beam evaporation)	US-PGPUB; USPAT	ADJ	ON	2007/12/13 17:43
S74	1159	(electron beam evaporation) and (magnetron sputtering)	US-PGPUB; USPAT	ADJ	ON	2007/12/13 17:44
S75	516	(electron beam evaporation) same (magnetron sputtering)	US-PGPUB; USPAT	ADJ	ON	2007/12/13 17:44
S76	377	(electron beam evaporation) with (magnetron sputtering)	US-PGPUB; USPAT	ADJ	ON	2007/12/13 17:44
S77	377	((electron beam evaporation) with (magnetron sputtering)) and (layer or coat or coating or film)	US-PGPUB; USPAT	ADJ	ON	2007/12/13 17:44
S78	54	((electron beam evaporation) with (magnetron sputtering)) and (layer or coat or coating or film) and "204".clas.	US-PGPUB; USPAT	ADJ	ON	2007/12/13 17:45
S79	25	("4663685" "4923585" "5014147" "5018037" "5089104").PN. OR ("5492605").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/10 17:36
S80	33	("3530057" "4853102" "4871433" "5006192" "5006219" "5026470" "5085755" "5178739" "5215638" "5308417" "5316645" "5346600" "5439574" "5455197" "5478459" "5630916" "5807467" "5922180"). PN. OR ("6077403"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/10 17:36
S81	8	("4142958" "4497700" "5851365" "5879519" "6039806" "RE32849"). PN. OR ("6635155"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/10 17:36

S82	23	("4180596" "4391846" "4629635" "4692343" "4737474" "4966869" "5183510" "5183782" "5203956" "5231056" "5326723" "5500249"). PN. OR ("5643633"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/06/10 17:36
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12/3/2008 4:15:40 PM

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